

# Gerburg Schider

## List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/3239981/publications.pdf>

Version: 2024-02-01

9  
papers

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citations

1478505

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1588992

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docs citations

9  
times ranked

225  
citing authors

#	ARTICLE	IF	CITATIONS
1	Printed Copper Nanoparticle Metal Grids for Cost-Effective ITO-Free Solution Processed Solar Cells. Solar Rrl, 2018, 2, 1700192.	5.8	31
2	Critical Evaluation of Organic Thin-Film Transistor Models. Crystals, 2019, 9, 85.	2.2	20
3	Interfacial Band Engineering of MoS <sub>2</sub> /Gold Interfaces Using Pyrimidine-Containing Self-Assembled Monolayers: Toward Contact-Resistance-Free Bottom-Contacts. Advanced Electronic Materials, 2020, 6, 2000110.	5.1	18
4	Up-scalable ITO-free organic light emitting diodes based on embedded inkjet-printed copper grids. Flexible and Printed Electronics, 2019, 4, 025004.	2.7	12
5	Microstructured single-layer electrodes embedded in P(VDF-TrFE) for flexible and self-powered direction-sensitive strain sensors. Smart Materials and Structures, 2020, 29, 085040.	3.5	12
6	Smart Core-Shell Nanostructures for Force, Humidity, and Temperature Multi-Stimuli Responsiveness. Advanced Materials Technologies, 2022, 7, .	5.8	10
7	A Two-Step Method to Covalently Bind Biomolecules to Group-IV Semiconductors: Si(111)/1,2-Epoxy-9-decene/Esterase. Langmuir, 2008, 24, 13957-13961.	3.5	6
8	2D Semiconductors: Interfacial Band Engineering of MoS <sub>2</sub> /Gold Interfaces Using Pyrimidine-Containing Self-Assembled Monolayers: Toward Contact-Resistance-Free Bottom-Contacts (Adv. Electron. Mater. 5/2020). Advanced Electronic Materials, 2020, 6, 2070026.	5.1	1
9	Large area processing and printing of conducting copper structures for use in (opto)electronics (Conference Presentation)., 2017, , .		0